TLA2528 小型 8 通道 12 位 ADC，具有 I²C 接口 及 GPIO

1 特性

- 小封装尺寸：
  - 3mm × 3mm WQFN
- 8 通道，可配置为以下任意组合：
  - 最多 8 个模拟输入、数字输入或数字输出
- 用于 I/O 扩展的 GPIO：
  - 开漏、推挽数字输出
- 宽工作范围：
  - AVDD：2.35V 至 5.5V
  - DVDD：1.65V 至 5.5V
  - 温度范围：–40°C 至 +85°C
- I²C 接口：
  - 高达 3.4MHz（高速）
  - 8 个可配置 I²C 地址
- 可编程均值滤波器:
  - 用于求平均值的可编程样本大小
  - 利用内部转换求平均值
  - 用于计算平均输出的 16 位分辨率

2 应用

- 监控功能
- 便携式仪表
- 电信基础设施
- 电源监控

3 说明

TLA2528 是一款易于使用的 8 通道多路复用 12 位逐次逼近寄存器模数转换器 (SAR ADC)。8 个通道可独立配置为模拟输入、数字输入或数字输出。该器件具有一个用于执行 ADC 转换过程的内部振荡器。

TLA2528 通过 I²C 兼容接口进行通信，支持标准模式 (100kHz)、快速模式 (400kHz)、快速模式+ (1MHz) 和高速模式 (3.4MHz)。通过在 ADDR 引脚上连接一个电阻，可为 TLA2528 选择最多 8 个 I²C 地址。

器件信息(1)

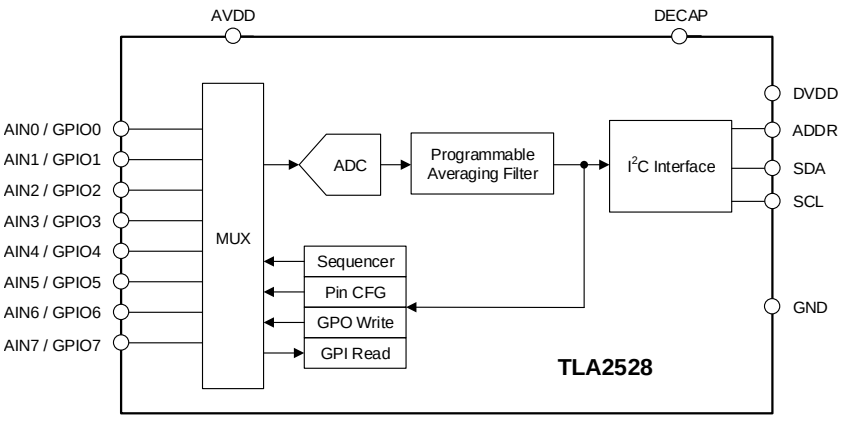
部件名称	封装	封装尺寸（标称值）
TLA2528	WQFN (16)	3.00mm × 3.00mm

(1) 如需了解所有可用封装，请见数据表末尾的可订购产品附录。

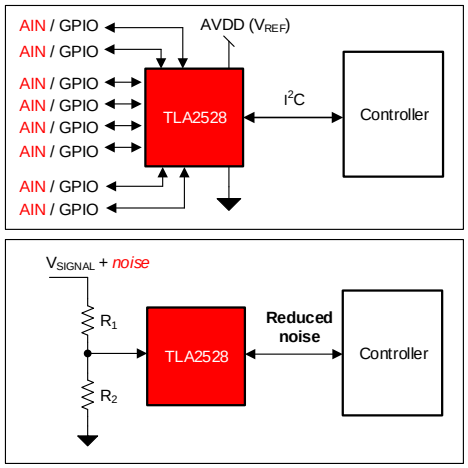
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TLA2528 方框图和 应用

Device Block Diagram



Example Applications



本文档旨在为方便起见，提供有关 TI 产品中文版本的信息，以确认产品的概要。 有关适用的官方英文版本的最新信息，请访问 www.ti.com，其内容始终优先。 TI 不保证翻译的准确性和有效性。 在实际设计之前，请务必参考最新版本的英文版本。

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4 修订历史记录

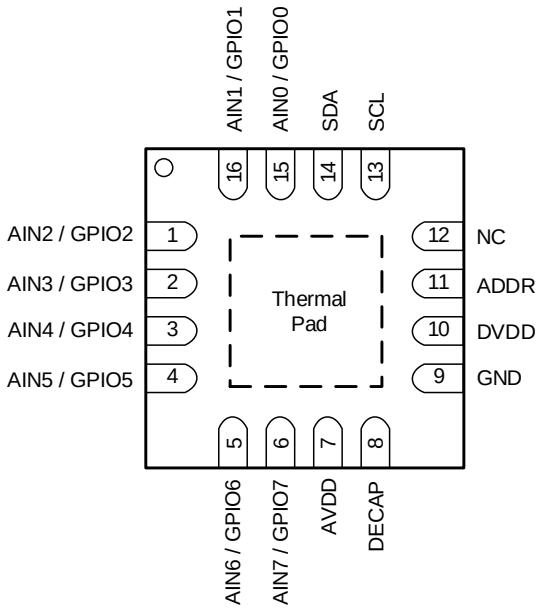
注：之前版本的页码可能与当前版本有所不同。

日期	修订版本	说明
2019 年 5 月	*	初始发行版。

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5 Pin Configuration and Functions

RTE Package
16-Pin WQFN
Top View



Pin Functions

PIN		FUNCTION(1)	DESCRIPTION
NAME	NO.		
AIN0/GPIO0	15	AI, DI, DO	Channel 0; configurable as either an analog input (default) or a general-purpose input/output (GPIO)
AIN1/GPIO1	16	AI, DI, DO	Channel 1; configurable as either an analog input (default) or a GPIO
AIN2/GPIO2	1	AI, DI, DO	Channel 2; configurable as either an analog input (default) or a GPIO
AIN3/GPIO3	2	AI, DI, DO	Channel 3; configurable as either an analog input (default) or a GPIO
AIN4/GPIO4	3	AI, DI, DO	Channel 4; configurable as either an analog input (default) or a GPIO
AIN5/GPIO5	4	AI, DI, DO	Channel 5; configurable as either an analog input (default) or a GPIO
AIN6/GPIO6	5	AI, DI, DO	Channel 6; configurable as either an analog input (default) or a GPIO
AIN7/GPIO7	6	AI, DI, DO	Channel 7; configurable as either an analog input (default) or a GPIO
ADDR	11	AI	Input for selecting the device I^2C address. Connect a resistor to this pin from DECAP pin or GND to select one of the eight addresses.
AVDD	7	Supply	Analog supply input, also used as the reference voltage to the ADC; connect a 1-µF decoupling capacitor to GND
DECAP	8	Supply	Connect a decoupling capacitor to this pin for the internal power supply
DVDD	10	Supply	Digital I/O supply voltage; connect a 1-µF decoupling capacitor to GND
GND	9	Supply	Ground for the power supply; all analog and digital signals are referred to this pin voltage
NC		No connection	This pin must be left floating with no external connection
SDA	14	DI, DO	Serial data input or output for the I^2C interface
SCL	13	DI	Serial clock for the I^2C interface

(1) AI = analog input, DI = digital input, and DO = digital output.

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6 Specifications

6.1 Absolute Maximum Ratings

over operating ambient temperature range (unless otherwise noted)(1)

	MIN	MAX	UNIT
DVDD to GND	–0.3	5.5	V
AVDD to GND	–0.3	5.5	V
AINx/GPOx(2)	GND – 0.3	AVDD + 0.3	V
ADDR	GND – 0.3	2.1	V
Digital inputs	GND – 0.3	5.5	V
Current through any pin except supply pins(3)	–10	10	mA
Junction temperature, T_J	–40	125	°C
Storage temperature, T_{stg}	–60	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) AINx/GPIOx refers to pins 1, 2, 3, 4, 5, 6, 15, and 16.
(3) Pin current must be limited to 10mA or less.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY						
AVDD	Analog supply voltage		2.35	3.3	5.5	V
DVDD	Digital supply voltage		1.65	3.3	5.5	V
ANALOG INPUTS						
FSR	Full-scale input range	AIN_X(1) - GND	0		AVDD	V
V_{IN}	Absolute input voltage	AIN_X - GND	–0.1		AVDD + 0.1	V
TEMPERATURE RANGE						
T_A	Ambient temperature		–40	25	85	℃

(1) AINx refers to AIN0, AIN1, AIN2, AIN3, AIN4, AIN5, AIN6, and AIN7.

6.4 Thermal Information

THERMAL METRIC(1)		TLA2528 RTE (WQFN) 16 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	49.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	53.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	24.7	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	1.3	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	24.7	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	9.3	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

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6.5 Electrical Characteristics

at AVDD = 5 V, DVDD = 1.65 V to 5.5 V, and maximum throughput (unless otherwise noted); minimum and maximum values at T_A = –40°C to +85°C; typical values at T_A = 25°C.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG INPUTS						
C_{SH}	Sampling capacitance			12		pF
DC PERFORMANCE						
	Resolution	No missing codes		12		bits
DNL	Differential nonlinearity			±0.3		LSB
INL	Integral nonlinearity			±0.5		LSB
$V_{(OS)}$	Input offset error	Post offset calibration		±0.5		LSB
	Input offset thermal drift	Post offset calibration		±5		ppm/°C
G_E	Gain error			±0.05		%FSR
	Gain error thermal drift			±5		ppm/°C
AC PERFORMANCE						
SINAD	Signal-to-noise + distortion ratio	AVDD = 5 V, f_{IN} = 2 kHz		71.5		dB
		AVDD = 3 V, f_{IN} = 2 kHz		70.5		
DECAP Pin						
	Decoupling capacitor on DECAP pin		0.22	1		µF
DIGITAL INPUT/OUTPUT (SCL, SDA)						
V_{IH}	Input high logic level	All I^2C modes	0.7 x DVDD		5.5	V
V_{IL}	Input low logic level	All I^2C modes	–0.3		0.3 x DVDD	V
V_{OL}	Output low logic level	Sink current = 2 mA, DVDD > 2 V	0		0.4	V
		Sink current = 2 mA, DVDD ≤ 2 V	0		0.2 x DVDD	
I_{OL}	Low-level output current (sink)	V_{OL} = 0.4 V, standard and fast mode			3	mA
		V_{OL} = 0.6 V, fast mode			6	
		V_{OL} = 0.4 V, fast mode plus			20	
GPIOs						
V_{IH}	Input high logic level		0.7 x AVDD		AVDD + 0.3	V
V_{IL}	Input low logic level		–0.3		0.3 x AVDD	V
V_{OH}	Output high logic level	GPO_DRIVE_CFG = push-pull, I_{SOURCE} = 2 mA	0.8 x AVDD		AVDD	V
V_{OL}	Output low logic level	I_{SINK} = 2 mA	0		0.2 x AVDD	V
I_{OH}	Output high source current	V_{OH} > 0.7 x AVDD			5	mA
I_{OL}	Output low sink current	V_{OL} < 0.3 x AVDD			5	mA
POWER SUPPLY CURRENTS						
I_{AVDD}	Analog supply current	I^2C high-speed mode, AVDD = 5 V		260		µA
		I^2C fast mode plus, AVDD = 5 V		83		
		I^2C fast mode, AVDD = 5 V		35		
		I^2C standard mode, AVDD = 5 V		10		
		No conversion, AVDD = 5 V		5		

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6.6 I²C Timing Requirements

		MODE				UNIT
		FAST MODE		HIGH SPEED MODE		
		MIN	MAX	MIN	MAX	
f_{SCL}	SCL clock frequency(1)		1		3.4	MHz
t_{SUSTA}	START condition setup time for repeated start	260		160		ns
t_{HDSTA}	Start condition hold time	260		160		ns
t_{LOW}	Clock low period	500		160		ns
t_{HIGH}	Clock high period	260		60		ns
t_{SUDAT}	Data in setup time	50		10		ns
t_{HDDAT}	Data in hold time	0		0		ns
t_R	SCL rise time		120		80	ns
t_F	SCL fall time		120		80	ns
t_{SUSTO}	STOP condition hold time	260		60		ns
t_{BUF}	Bus free time before new transmission	500		300		ns

(1) Bus load (C_B) consideration; $C_B \leq 400$ pF for $f_{SCL} \leq 1$ MHz; $C_B < 100$ pF for $f_{SCL} = 3.4$ MHz.

6.7 Timing Requirements

at AVDD = 2.35 V to 5 V, DVDD = 1.65 V to 5.5 V, and maximum throughput (unless otherwise noted); minimum and maximum values at T_A = –40°C to +85°C; typical values at T_A = 25°C.

		MIN	MAX	UNIT
t_{ACQ}	Acquisition time	300		ns

6.8 I²C Switching Characteristics

		MODE				UNIT
		FAST MODE		HIGH-SPEED MODE		
		MIN	MAX	MIN	MAX	
t_{VDDATA}	SCL low to SDA data out valid		450		200	ns
t_{VDACK}	SCL low to SDA acknowledge time		450		200	ns
$t_{STRETCH}$	Clock stretch time in one-shot conversion mode; during ADC conversion		1200		950	ns
t_{SP}	Noise supression time constant on SDA and SCL		50		10	ns

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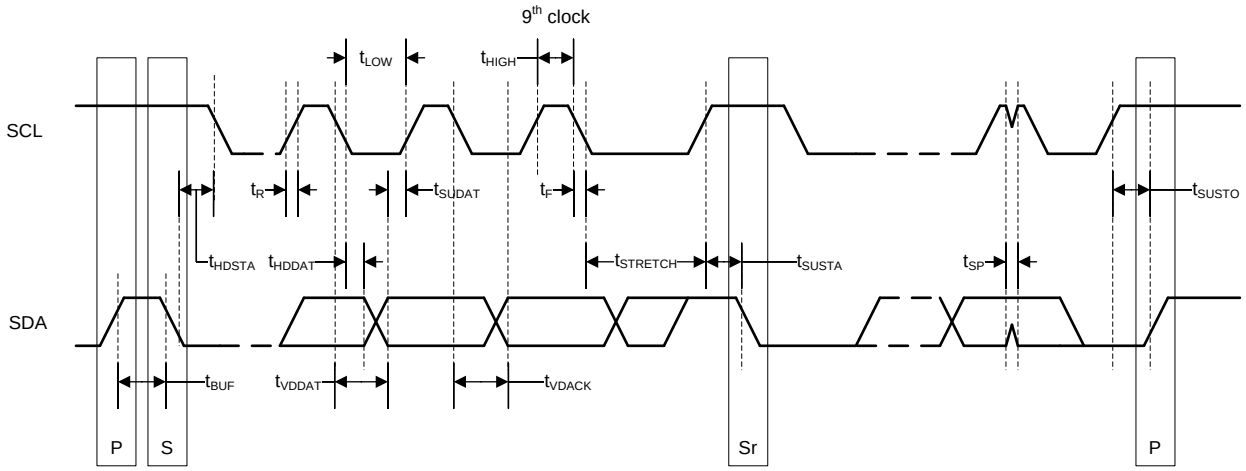
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6.9 Switching Characteristics

at AVDD = 2.35 V to 5 V, DVDD = 1.65 V to 5.5 V, and maximum throughput (unless otherwise noted); minimum and maximum values at T_A = –40°C to +85°C; typical values at T_A = 25°C.

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
CONVERSION CYCLE					
t_{CONV}	ADC conversion time			$t_{STRETCH}$	ns
RESET					
t_{PU}	Power-up time for device	AVDD ≥ 2.35 V		5	ms
t_{RST}	Delay time; RST bit = 1b to device reset complete (1)			5	ms

(1) RST bit is automatically reset to 0b after t_{RST}.



NOTE: S = start, Sr = repeated start, and P = stop.

图 1. I²C Timing Diagram

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7 Detailed Description

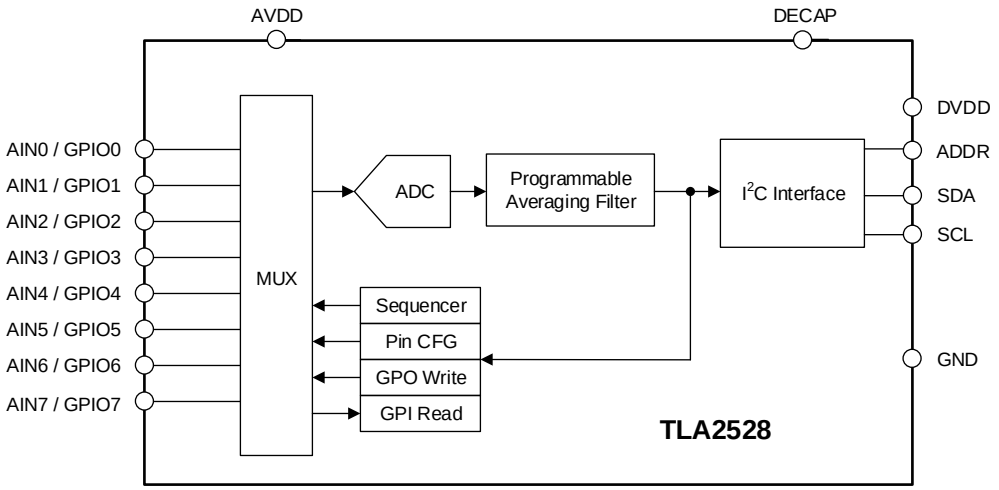
7.1 Overview

The TLA2528 is a small, eight-channel, multiplexed, 12-bit, analog-to-digital converter (ADC) with an I^2C-compatible serial interface. The eight channels of the TLA2528 can be individually configured as either analog inputs, digital inputs, or digital outputs. The device uses an internal oscillator for conversion. The analog input channel selection can be auto-sequenced to simplify the digital interface with the host.

The device features a programmable averaging filter that outputs a 16-bit result for enhanced resolution.

The I^2C serial interface supports standard-mode, fast-mode, fast-mode plus, and high-speed mode.

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Multiplexer and ADC

The eight channels of the multiplexer can be independently configured as ADC inputs or general-purpose inputs/outputs (GPIOs). 图 2 shows that each input pin has electrostatic discharge (ESD) protection diodes to AVDD and GND. On power-up or after device reset, all eight multiplexer channels are configured as analog inputs.

图 2 shows an equivalent circuit for pins configured as analog inputs. The ADC sampling switch is represented by an ideal switch (SW) in series with the resistor, R_{SW} (typically 150 Ω), and the sampling capacitor, C_{SH} (typically 12 pF).

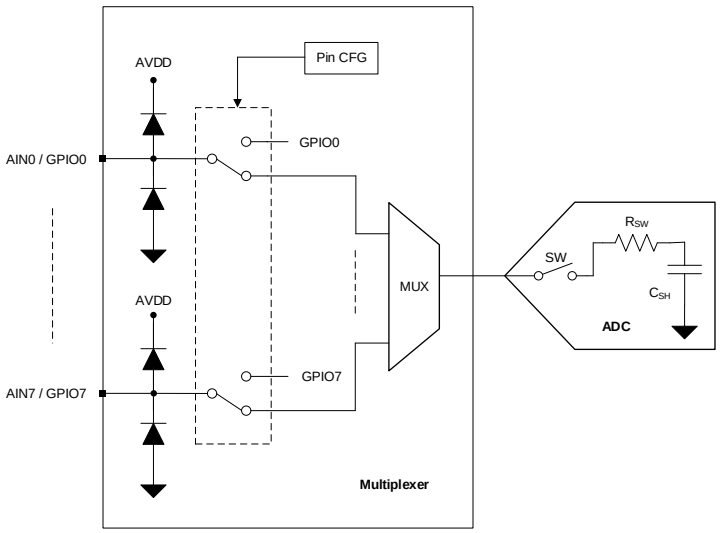


图 2. Analog Inputs, GPIOs, and ADC Connections

During acquisition, the SW switch is closed to allow the signal on the selected analog input channel to charge the internal sampling capacitor. During conversion, the SW switch is opened to disconnect the analog input channel from the sampling capacitor.

The multiplexer channels can be configured as GPIOs in the PIN_CFG register. The direction of a GPIO (either as an input or an output) can be set in the GPIO_CFG register. The logic level on the channels configured as digital inputs can be read from the GPI_VALUE register. The digital outputs can be accessed by writing to the GPO_OUTPUT_VALUE register. The digital outputs can be configured as either open-drain or push-pull in the GPO_DRIVE_CFG register.

7.3.2 Reference

The device uses the analog supply voltage (AVDD) as a reference for the analog-to-digital conversion process. TI recommends connecting a 1-µF, low-equivalent series resistance (ESR) ceramic decoupling capacitor between the AVDD and GND pins.

7.3.3 ADC Transfer Function

The ADC output is in straight binary format. 公式 1 computes the ADC resolution:

$$1\ LSB = V_{REF} / 2^N \quad (1)$$

where:

- V_{REF} = AVDD
- N = 12

图 3 and 表 1 detail the transfer characteristics for the device.

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Feature Description (接下页)

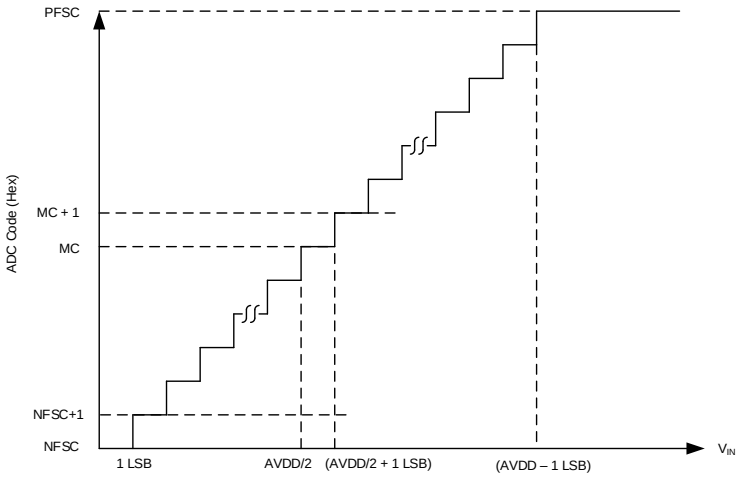


图 3. Ideal Transfer Characteristics

表 1. Transfer Characteristics

INPUT VOLTAGE	CODE	DESCRIPTION	IDEAL OUTPUT CODE
≤1 LSB	NFSC	Negative full-scale code	000
1 LSB to 2 LSBs	NFSC + 1	—	001
(AVDD / 2) to (AVDD / 2) + 1 LSB	MC	Mid code	800
(AVDD / 2) + 1 LSB to (AVDD / 2) + 2 LSB	MC + 1	—	801
≥ AVDD – 1 LSB	PFSC	Positive full-scale code	FFF

7.3.4 ADC Offset Calibration

The variation in ADC offset error resulting from changes in temperature or AVDD can be calibrated by setting the CAL bit in the GENERAL_CFG register. The CAL bit is reset to 0 after calibration. The host can poll the CAL bit to check the ADC offset calibration completion status.

7.3.5 I^2C Address Selector

The I^2C address for the device is determined by connecting external resistors on the ADDR pin. The device address is determined at power-up based on the resistor values. The device retains this address until the next power-up event, until the next device reset, or until the device receives a command to program its own address. 图 4 shows a connection diagram for the ADDR pin and 表 2 lists the resistor values for selecting different addresses of the device.

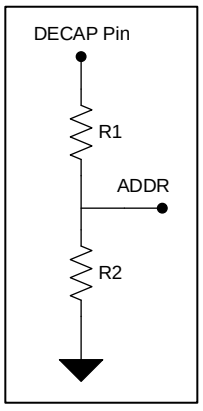


图 4. External Resistor Connection Diagram for the ADDR Pin

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表 2. I²C Address Selection

RESISTORS		ADDRESS
R1(1)	R2(1)	
0 Ω	DNP(2)	001 0111b (17h)
11 kΩ	DNP(2)	001 0110b (16h)
33 kΩ	DNP(2)	001 0101b (15h)
100 kΩ	DNP(2)	001 0100b (14h)
DNP(2)	0 Ω or DNP(2)	001 0000b (10h)
DNP(2)	11 kΩ	001 0001b (11h)
DNP(2)	33 kΩ	001 0010b (12h)
DNP(2)	100 kΩ	001 0011b (13h)

(1) Tolerance for R1, R2 ≤ ±5%.
(2) DNP = Do not populate.

7.3.6 Programmable Averaging Filter

The ADS7138 features a built-in oversampling (OSR) function that can be used to average several samples. The averaging filter can be enabled by programming the OSR[2:0] bits in the OSR_CFG register. The averaging filter configuration is common to all analog input channels. 图 5 shows that the averaging filter module output is 16 bits long. In the manual conversion mode and auto-sequence mode, only the first conversion for the selected analog input channel must be initiated by the host; see the *Manual Mode* and *Auto-Sequence Mode* sections. As shown in 图 5, any remaining conversions for the selected averaging factor are generated internally. The time required to complete the averaging operation is determined by the sampling speed and number of samples to be averaged. As shown in 图 5, the 16-bit result can be read out after the averaging operation completes.

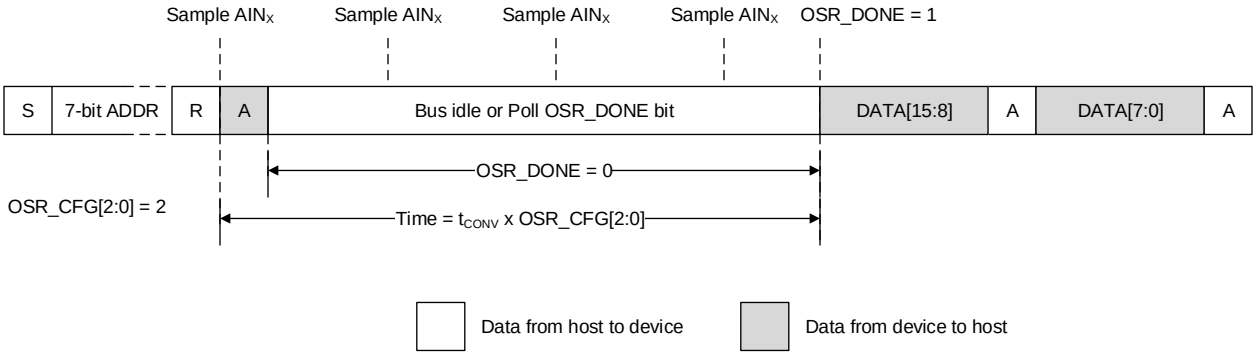


图 5. Averaging Example

In 图 5, SCL is stretched by the device after the start of conversions until the averaging operation is complete.

If SCL stretching is not required during averaging, enable the statistics registers by setting STATS_EN to 1b and initiate conversions by writing 1b to the CNVST bit. The OSR_DONE bit in the SYSTEM_STATUS register can be polled to check the averaging completion status. When using the CNVST bit to initiate conversion, the result can be read in the RECENT_CHx_LSB and RECENT_CHx_MSB registers.

公式 2 provides the LSB value of the 16-bit average result.

$$1\ LSB = \frac{AVDD}{2^{16}} \quad (2)$$

7.3.7 General-Purpose I/Os (GPIOs)

The eight channels of the TLA2528 can be independently configured as analog inputs, digital inputs, or digital outputs. 表 3 describes how the PIN_CFG and GPIO_CFG registers can be used to configure the channels.

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表 3. Configuring Channels as Analog Inputs or GPIOs

PIN_CFG[7:0]	GPIO_CFG[7:0]		GPO_DRIVE_CFG[7:0]	CHANNEL CONFIGURATION
0	x		x	Analog input (default)
1	0		x	Digital input
1	1		0	Digital output; open-drain driver
1	1		1	Digital output; push-pull driver

The digital outputs can be configured to logic 1 or 0 by writing to the GPO_OUTPUT_VALUE register. Reading the GPI_VALUE register returns the logic level for all channels configured as digital inputs.

7.3.8 Oscillator and Timing Control

The device uses an internal oscillator for conversions. When using the averaging module, the host initiates the first conversion and all subsequent conversions are generated internally by the device. However, in the autonomous mode of operation, the start of the conversion signal is generated by the device. 表 4 shows that when the device generates the start of the conversion, the sampling rate is controlled by the OSC_SEL and CLK_DIV[3:0] register fields.

表 4. Configuring Sampling Rate for Internal Conversion Start Control

CLK_DIV[3:0]	OSC_SEL = 0		OSC_SEL = 1	
	SAMPLING FREQUENCY, f_{CYCLE} (kSPS)	CYCLE TIME, t_{CYCLE} (µs)	SAMPLING FREQUENCY, f_{CYCLE} (kSPS)	CYCLE TIME, t_{CYCLE} (µs)
0000b	1000	1	31.25	32
0001b	666.7	1.5	20.83	48
0010b	500	2	15.63	64
0011b	333.3	3	10.42	96
0100b	250	4	7.81	128
0101b	166.7	6	5.21	192
0110b	125	8	3.91	256
0111b	83	12	2.60	384
1000b	62.5	16	1.95	512
1001b	41.7	24	1.3	768
1010b	31.3	32	0.98	1024
1011b	20.8	48	0.65	1536
1100b	15.6	64	0.49	2048
1101b	10.4	96	0.33	3072

The conversion time of the device (see t_{CONV} in the *Switching Characteristics* table) is independent of the OSC_SEL and CLK_DIV[3:0] configuration.

7.3.9 Output Data Format

图 6 illustrates various I^2C frames for reading data.

- Read the ADC conversion result: Two 8-bit I^2C packets are required (frame A).
- Read the averaged conversion result: Two 8-bit I^2C packets are required (frame B).
- Read data with the channel ID or status flags appended: The 4-bit channel ID or status flags can be appended to the 12-bit ADC result by configuring the APPEND_STATUS field in the GENERAL_CFG register. The status flags can be used to detect if a CRC error is detected and if an alert condition is detected by the digital window comparator. When the channel ID is or status flags are appended to the 12-bit ADC data, two I^2C packets are required (frame C). If the channel ID is or status flags are appended to the 16-bit average result, three I^2C frames are required (frame D).

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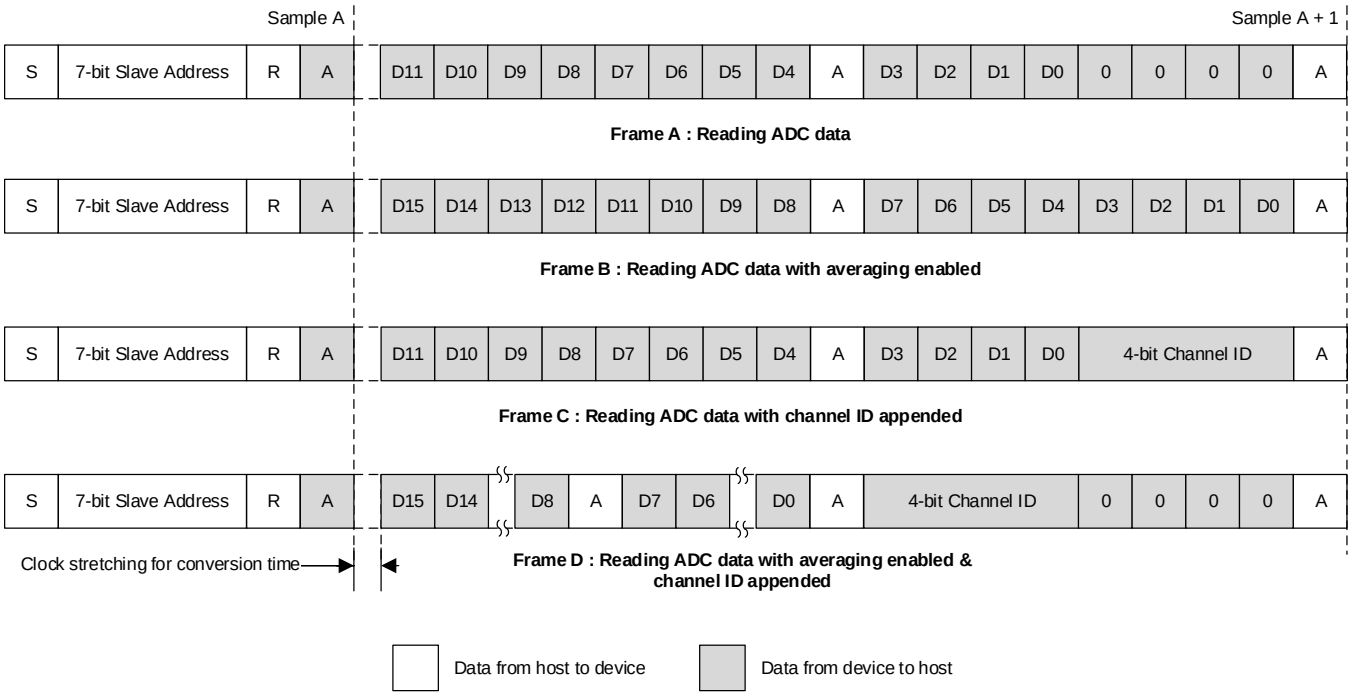


图 6. Data Frames for Reading Data

7.3.10 I²C Protocol Features

7.3.10.1 General Call

On receiving a general call (00h), the device provides an acknowledge (ACK).

7.3.10.2 General Call With Software Reset

On receiving a general call (00h) followed by a software reset (06h), the device resets itself.

7.3.10.3 General Call With a Software Write to the Programmable Part of the Slave Address

On receiving a general call (00h) followed by 04h, the device reevaluates its own I²C address configured by the ADDR pin. During this operation, the device does not respond to other I²C commands except the general-call command.

7.3.10.4 Configuring the Device for High-Speed I²C Mode

The device can be configured in high-speed I²C mode by providing an I²C frame with one of these codes: 0x09, 0x0B, 0x0D, or 0x0F.

After receiving one of these codes, the device sets the I2C_HIGH_SPEED bit in the SYSTEM_STATUS register and remains in high-speed I²C mode until a STOP condition is received in an I²C frame.

7.4 Device Functional Modes

表 5 lists the functional modes supported by the TLA2528.

表 5. Functional Modes

FUNCTIONAL MODE	CONVERSION CONTROL	MUX CONTROL	SEQ_MODE[1:0]
Manual	9th falling edge of SCL (ACK)	Register write to MANUAL_CHID	00b
Auto-sequence	9th falling edge of SCL (ACK)	Channel sequencer	01b

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The device powers up in manual mode (see the *Manual Mode* section) and can be configured into any mode listed in 表 5 by writing the configuration registers for the desired mode.

7.4.1 Device Power-Up and Reset

On power-up, the device calculates the address from the resistors connected on the ADDR pin and the BOR bit is set, thus indicating a power-cycle or reset event.

The device can be reset by an I^2C general call (00h) followed by a software reset (06h), by setting the RST bit, or by recycling the power on the AVDD pin.

7.4.2 Manual Mode

Manual mode allows the external host processor to directly select the analog input channel. 图 7 lists the steps for operating the device in manual mode.

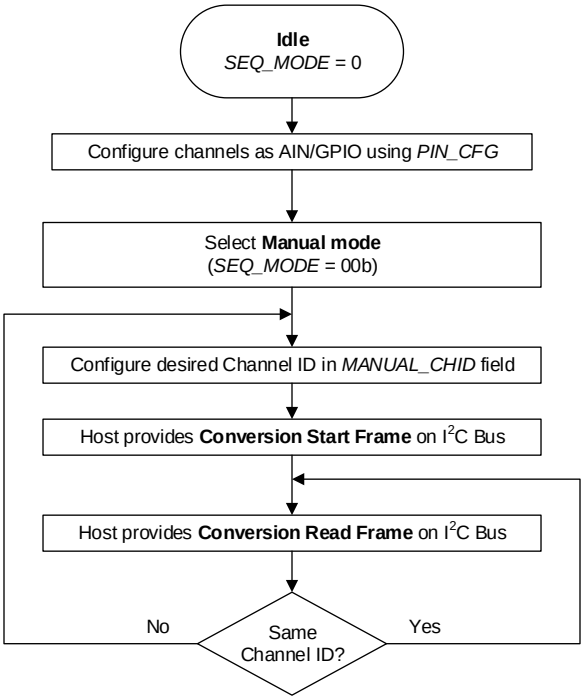


图 7. Device Operation in Manual Mode

Provide an I^2C start or restart frame to initiate a conversion, as shown in the conversion start frame of 图 8, after configuring the device registers. ADC data can be read in subsequent I^2C frames. The number of I^2C frames required to read conversion data depends on the output data frame size; see the *Output Data Format* section for more details. A new conversion is initiated on the ninth falling edge of SCL (ACK bit) when the last byte of output data is read.

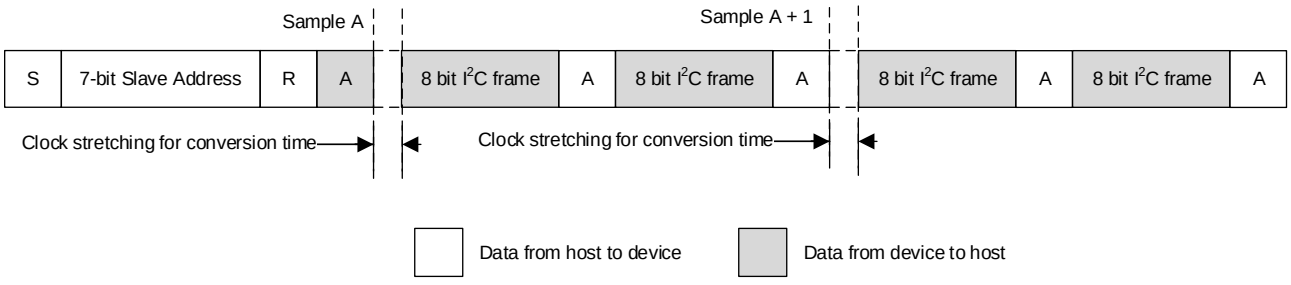


图 8. Starting a Conversion and Reading Data in Manual Mode

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7.4.3 Auto-Sequence Mode

In auto-sequence mode, the internal channel sequencer switches the multiplexer to the next analog input channel after every conversion. The desired analog input channels can be configured for sequencing in the AUTO_SEQ_CHSEL register. To enable the channel sequencer, set SEQ_START to 1b. After every conversion, the channel sequencer switches the multiplexer to the next analog input in ascending order. To stop the channel sequencer from selecting channels, set SEQ_START to 0b. 图 9 lists the conversion start and read frames for auto-sequence mode.

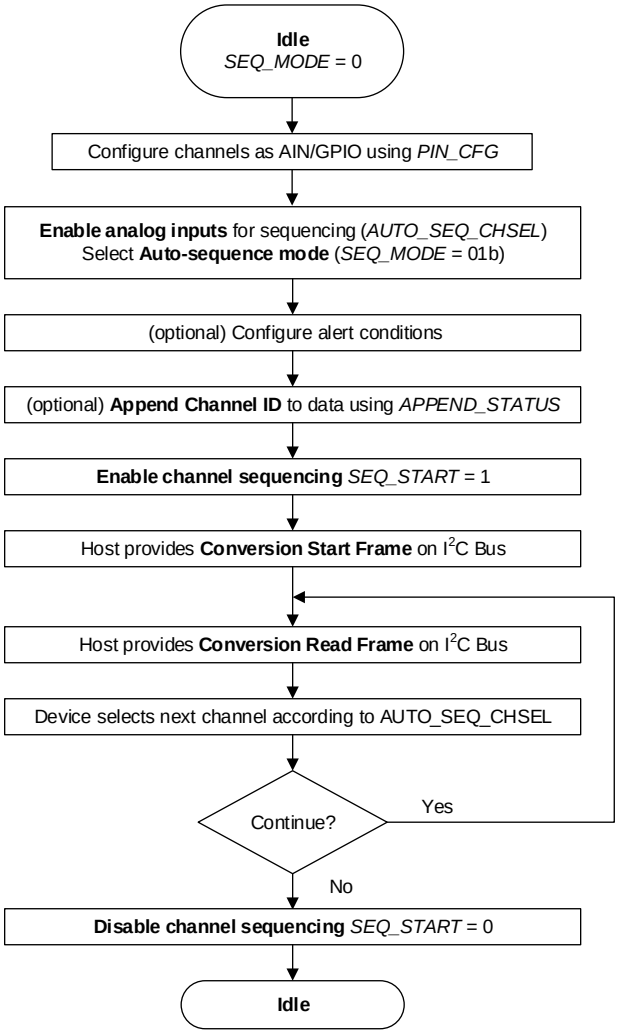


图 9. Device Operation in Auto-Sequence Mode

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7.5 Programming

表 6 provides the acronyms for different conditions in an I²C frame. 表 7 lists the various command opcodes.

表 6. I²C Frame Acronyms

SYMBOL	DESCRIPTION
S	Start condition for the I²C frame
Sr	Restart condition for the I²C frame
P	Stop condition for the I²C frame
A	ACK (low)
N	NACK (high)
R	Read bit (high)
W	Write bit (low)

表 7. Opcodes for Commands

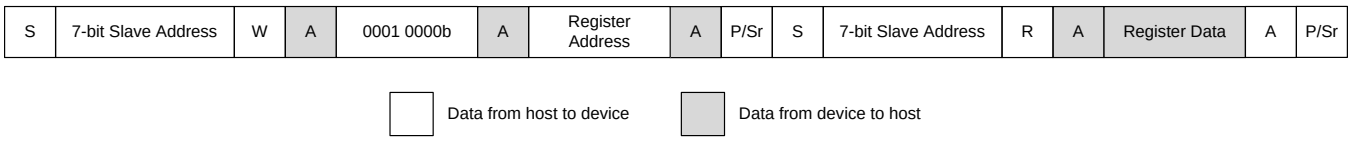
OPCODE	COMMAND DESCRIPTION
0001 0000b	Single register read
0000 1000b	Single register write
0001 1000b	Set bit
0010 0000b	Clear bit
0011 0000b	Reading a continuous block of registers
0010 1000b	Writing a continuous block of registers

7.5.1 Reading Registers

The I²C master can either read a single register or a continuous block registers from the device, as described in the *Single Register Read* and *Reading a Continuous Block of Registers* sections.

7.5.1.1 Single Register Read

To read a single register from the device, the I²C master must provide an I²C command with three frames to set the register address for reading data. 表 7 lists the opcodes for different commands. After this command is provided, the I²C master must provide another I²C frame (as shown in 图 10) containing the device address and the read bit. After this frame, the device provides the register data. The device provides the same register data even if the host provides more clocks. To end the register read command, the master must provide a STOP or a RESTART condition in the I²C frame.



NOTE: S = start, Sr = repeated start, and P = stop.

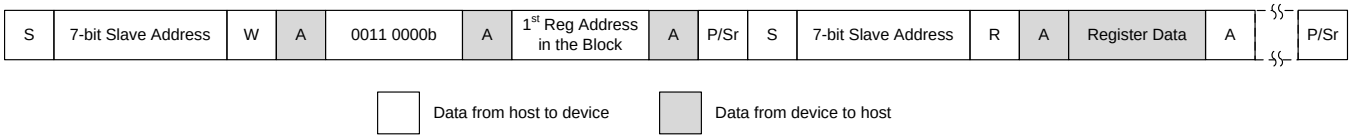
图 10. Reading Register Data

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7.5.1.2 Reading a Continuous Block of Registers

To read a continuous block of registers, the I²C master must provide an I²C command to set the register address. The register address is the address of the first register in the block that must be read. After this command is provided, the I²C master must provide another I²C frame, as shown in 图 11, containing the device address and the read bit. After this frame, the device provides the register data. The device provides data for the next register when more clocks are provided. When data are read from addresses that do not exist in the register map of the device, the device returns zeros. If the device does not have any further registers to provide data on, the device provide zeros. To end the register read command, the master must provide a STOP or a RESTART condition in the I²C frame.



NOTE: S = start, Sr = repeated start, and P = stop.

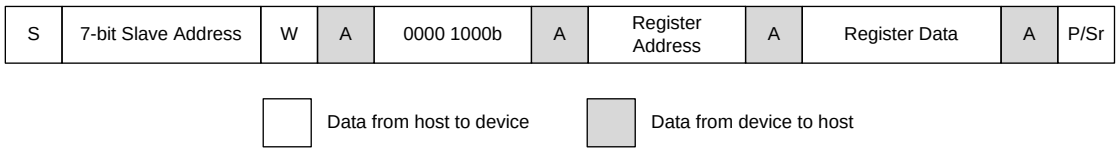
图 11. Reading a Continuous Block of Registers

7.5.2 Writing Registers

The I²C master can either write a single register or a continuous block of registers to the device, set a few bits in a register, or clear a few bits in a register.

7.5.2.1 Single Register Write

To write a single register from the device, as shown in 图 12, the I²C master must provide an I²C command with four frames. The register address is the address of the register that must be written and the register data is the value that must be written. 表 7 lists the opcodes for different commands. To end the register write command, the master must provide a STOP or a RESTART condition in the I²C frame.



NOTE: S = start, Sr = repeated start, and P = stop.

图 12. Writing a Single Register

7.5.2.2 Set Bit

The I²C master must provide an I²C command with four frames, as shown in 图 12, to set bits in a register without changing the other bits. The register address is the address of the register that the bits must set and the register data is the value representing the bits that must be set. Bits with a value of 1 in the register data are set and bits with a value of 0 in the register data are not changed. 表 7 lists the opcodes for different commands. To end this command, the master must provide a STOP or RESTART condition in the I²C frame.

7.5.2.3 Clear Bit

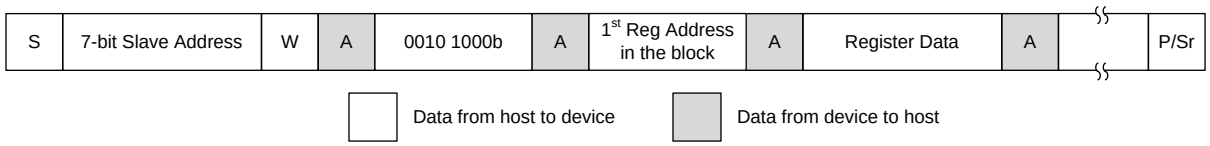
The I²C master must provide an I²C command with four frames, as shown in 图 12, to clear bits in a register without changing the other bits. The register address is the address of the register that the bits must clear and the register data is the value representing the bits that must be cleared. Bits with a value of 1 in the register data are cleared and bits with a value of 0 in the register data are not changed. 表 7 lists the opcodes for different commands. To end this command, the master must provide a STOP or a RESTART condition in the I²C frame.

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7.5.2.4 Writing a Continuous Block of Registers

The I²C master must provide an I²C command, as shown in 图 13, to write a continuous block of registers. The register address is the address of the first register in the block that must be written. The I²C master must provide data for registers in subsequent I²C frames in an ascending order of register addresses. Writing data to addresses that do not exist in the register map of the device have no effect. 表 7 lists the opcodes for different commands. If the data provided by the I²C master exceeds the address space of the device, the device ignores the data beyond the address space. To end the register write command, the master must provide a STOP or a RESTART condition in the I²C frame.



NOTE: S = start, Sr = repeated start, and P = stop.

图 13. Writing a Continuous Block of Registers

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7.6 TLA2528 Registers

Table 8 lists the TLA2528 registers. All register offset addresses not listed in Table 8 should be considered as reserved locations and the register contents should not be modified.

Table 8. TLA2528 Registers

Address	Acronym	Register Name	Section
0x0	SYSTEM_STATUS		SYSTEM_STATUS Register (Address = 0x0) [reset = 0x80]
0x1	GENERAL_CFG		GENERAL_CFG Register (Address = 0x1) [reset = 0x0]
0x2	DATA_CFG		DATA_CFG Register (Address = 0x2) [reset = 0x0]
0x3	OSR_CFG		OSR_CFG Register (Address = 0x3) [reset = 0x0]
0x4	OPMODE_CFG		OPMODE_CFG Register (Address = 0x4) [reset = 0x0]
0x5	PIN_CFG		PIN_CFG Register (Address = 0x5) [reset = 0x0]
0x7	GPIO_CFG		GPIO_CFG Register (Address = 0x7) [reset = 0x0]
0x9	GPO_DRIVE_CFG		GPO_DRIVE_CFG Register (Address = 0x9) [reset = 0x0]
0xB	GPO_OUTPUT_VALUE		GPO_OUTPUT_VALUE Register (Address = 0xB) [reset = 0x0]
0xD	GPI_VALUE_LSB		GPI_VALUE_LSB Register (Address = 0xD) [reset = 0x0]
0x10	SEQUENCE_CFG		SEQUENCE_CFG Register (Address = 0x10) [reset = 0x0]
0x11	CHANNEL_SEL		CHANNEL_SEL Register (Address = 0x11) [reset = 0x0]
0x12	AUTO_SEQ_CHSEL		AUTO_SEQ_CHSEL Register (Address = 0x12) [reset = 0x0]

Complex bit access types are encoded to fit into small table cells. Table 9 shows the codes that are used for access types in this section.

Table 9. TLA2528 Access Type Codes

Access Type	Code	Description
Read Type		
R	R	Read
Write Type		
W	W	Write
Reset or Default Value		
-*n*		Value after reset or the default value
Register Array Variables		
i,j,k,l,m,n		When these variables are used in a register name, an offset, or an address, they refer to the value of a register array where the register is part of a group of repeating registers. The register groups form a hierarchical structure and the array is represented with a formula.
y		When this variable is used in a register name, an offset, or an address it refers to the value of a register array.

7.6.1 SYSTEM_STATUS Register (Address = 0x0) [reset = 0x80]

SYSTEM_STATUS is shown in Figure 14 and described in Table 10.

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Figure 14. SYSTEM_STATUS Register

7	6	5	4	3	2	1	0
RSVD	SEQ_STATUS	I²C_SPEED	RESERVED	OSR_DONE	CRC_ERR_FUSE	RESERVED	BOR
R-1b	R-0b	R-0b	R-0b	R/W-0b	R-0b	R-0b	R/W-0b

Table 10. SYSTEM_STATUS Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RSVD	R	1b	This bit must read 1b.
6	SEQ_STATUS	R	0b	Sequencer Status 0b = Sequence stopped 1b = Sequence in progress
5	I²C_SPEED	R	0b	I²C high-speed status 0b = Device is not in high speed mode 1b = Device is in high speed mode
4	RESERVED	R	0b	Reserved. Reads return 0b.
3	OSR_DONE	R/W	0b	OSR status. Clear this bit by writing 1b to this bit. 0b = OSR in progress; data not ready. 1b = OSR complete; data ready.
2	CRC_ERR_FUSE	R	0b	Device fuse CRC check status. To re-evaluate this bit, software reset the device or power cycle AVDD. 0b = Configuration is good. 1b = Device configuration not loaded correctly.
1	RESERVED	R	0b	Reserved. Reads return 0b.
0	BOR	R/W	0b	Brown out reset indicator. This bit is set if brown out condition occurs or device is power cycled. Write 1 to this bit to clear the flag. 0b = No brown out from last time this bit was cleared. 1b = Brown out condition detected or device power cycled.

7.6.2 GENERAL_CFG Register (Address = 0x1) [reset = 0x0]

GENERAL_CFG is shown in Figure 15 and described in Table 11.

Return to the Summary Table.

Figure 15. GENERAL_CFG Register

7	6	5	4	3	2	1	0
RESERVED				CNVST	CH_RST	CAL	RST
R-0b				W-0b	R/W-0b	R/W-0b	W-0b

Table 11. GENERAL_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0b	Reserved. Reads return 0b.
3	CNVST	W	0b	Intiate start of conversion. Readback of this bit will return 0. 0b = Normal operation. 1b = Initiate start of conversion.
2	CH_RST	R/W	0b	Force all channels to be analog inputs. 0b = Normal operation. 1b = All channels will be set as analog inputs irrespective of configuration in other registers.
1	CAL	R/W	0b	Calibrate ADC offset. 0b = Normal operation. 1b = ADC offset will be calibrated. After calibration is complete, this bit will be set to 0.

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Table 11. GENERAL_CFG Register Field Descriptions (continued)

Bit	Field	Type	Reset	Description
0	RST	W	0b	Software reset all registers to default values. 0b = Normal operation. 1b = Device will be reset. After reset is complete, this bit will be set to 0.

7.6.3 DATA_CFG Register (Address = 0x2) [reset = 0x0]

DATA_CFG is shown in Figure 16 and described in Table 12.

Return to the Summary Table.

Figure 16. DATA_CFG Register

7	6	5	4	3	2	1	0
FIX_PAT	RESERVED	APPEND_STATUS[1:0]		RESERVED			
R/W-0b	R-0b	R/W-0b		R-0b			

Table 12. DATA_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7	FIX_PAT	R/W	0b	Device outputs fixed data bits. Helpful for debugging device communication. 0b = Normal operation. 1b = Device outputs a fixed code 0xA5A repeatitively when reading ADC data.
6	RESERVED	R	0b	Reserved. Reads return 0b.
5-4	APPEND_STATUS[1:0]	R/W	0b	Append 4-bit channel ID to output data. 0b = Flag is not appended to ADC data. 1b = Channel ID is appended to ADC data.
3-0	RESERVED	R	0b	Reserved. Reads return 0b.

7.6.4 OSR_CFG Register (Address = 0x3) [reset = 0x0]

OSR_CFG is shown in Figure 17 and described in Table 13.

Return to the Summary Table.

Figure 17. OSR_CFG Register

7	6	5	4	3	2	1	0
RESERVED						OSR[2:0]	
R-0b						R/W-0b	

Table 13. OSR_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R	0b	Reserved. Reads return 0b.
2-0	OSR[2:0]	R/W	0b	Selects the oversampling ratio for ADC conversion result. 0b = OSR = 0. 1b = OSR = 2. 10b = OSR = 4. 11b = OSR = 8. 100b = OSR = 16. 101b = OSR = 32. 110b = OSR = 64. 111b = OSR = 128.

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7.6.5 OPMODE_CFG Register (Address = 0x4) [reset = 0x0]

OPMODE_CFG is shown in Figure 18 and described in Table 14.

Return to the Summary Table.

Figure 18. OPMODE_CFG Register

7	6	5	4	3	2	1	0
RESERVED			OSC_SEL	CLK_DIV[3:0]			
R-0b			R/W-0b	R/W-0b			

Table 14. OPMODE_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R	0b	Reserved. Reads return 0b.
4	OSC_SEL	R/W	0b	Selects the oscillator for internal timing generation. 0b = High speed oscillator. 1b = Low power oscillator.
3-0	CLK_DIV[3:0]	R/W	0b	Sampling speed control. Refer to section on Oscillator and Timing Control for details.

7.6.6 PIN_CFG Register (Address = 0x5) [reset = 0x0]

PIN_CFG is shown in Figure 19 and described in Table 15.

Return to the Summary Table.

Figure 19. PIN_CFG Register

7	6	5	4	3	2	1	0
PIN_CFG[7:0]							
R/W-0b							

Table 15. PIN_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	PIN_CFG[7:0]	R/W	0b	Configure device channels CH7 through CH0 as analog input or GPIO. 0b = Channel is configured as analog input. 1b = Channel is configured as GPIO.

7.6.7 GPIO_CFG Register (Address = 0x7) [reset = 0x0]

GPIO_CFG is shown in Figure 20 and described in Table 16.

Return to the Summary Table.

Figure 20. GPIO_CFG Register

7	6	5	4	3	2	1	0
GPIO_CFG[7:0]							
R/W-0b							

Table 16. GPIO_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	GPIO_CFG[7:0]	R/W	0b	Configure GPIO7 through GPIO0 as either digital input or digital output. 0b = GPIO is digital input. 1b = GPIO is digital output.

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7.6.8 GPO_DRIVE_CFG Register (Address = 0x9) [reset = 0x0]

GPO_DRIVE_CFG is shown in Figure 21 and described in Table 17.

Return to the Summary Table.

Figure 21. GPO_DRIVE_CFG Register

7	6	5	4	3	2	1	0
GPO_DRIVE_CFG[7:0]							
R/W-0b							

Table 17. GPO_DRIVE_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	GPO_DRIVE_CFG[7:0]	R/W	0b	Configure digital outputs GPO7 through GPO0 as open-drain or push-pull output. 0b = Digital output is open-drain. Connect external pullup. 1b = Digital output is push-pull.

7.6.9 GPO_OUTPUT_VALUE Register (Address = 0xB) [reset = 0x0]

GPO_OUTPUT_VALUE is shown in Figure 22 and described in Table 18.

Return to the Summary Table.

Figure 22. GPO_OUTPUT_VALUE Register

7	6	5	4	3	2	1	0
GPO_OUTPUT_VALUE[7:0]							
R/W-0b							

Table 18. GPO_OUTPUT_VALUE Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	GPO_OUTPUT_VALUE[7:0]	R/W	0b	Logic level to be set on digital outputs GPO[7:0]. 0b = Digital output set to logic 0. 1b = Digital output set to logic 1.

7.6.10 GPI_VALUE_LSB Register (Address = 0xD) [reset = 0x0]

GPI_VALUE_LSB is shown in Figure 23 and described in Table 19.

Return to the Summary Table.

Figure 23. GPI_VALUE_LSB Register

7	6	5	4	3	2	1	0
GPI_VALUE[7:0]							
R-0b							

Table 19. GPI_VALUE_LSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	GPI_VALUE[7:0]	R	0b	Readback the logic level on digital input. 0b = Digital input is at logic 0. 1b = Digital input is at logic 1.

7.6.11 SEQUENCE_CFG Register (Address = 0x10) [reset = 0x0]

SEQUENCE_CFG is shown in Figure 24 and described in Table 20.

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Figure 24. SEQUENCE_CFG Register

7	6	5	4	3	2	1	0
RESERVED			SEQ_START	RESERVED		SEQ_MODE[1:0]	
R-0b			R/W-0b	R-0b		R/W-0b	

Table 20. SEQUENCE_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R	0b	Reserved. Reads return 0b.
4	SEQ_START	R/W	0b	Sequence start control when using auto sequence mode. 0b = Stop auto sequencing. 1b = Start auto sequencing from first enabled analog input channel starting from channel ID = 0 (ascending order).
3-2	RESERVED	R	0b	Reserved. Reads return 0b.
1-0	SEQ_MODE[1:0]	R/W	0b	Selects the mode of scanning analog input channels. 0b = Manual sequence mode. 1b = Auto sequence mode. 10b = Reserved. 11b = Reserved.

7.6.12 CHANNEL_SEL Register (Address = 0x11) [reset = 0x0]

CHANNEL_SEL is shown in Figure 25 and described in Table 21.

Return to the Summary Table.

Figure 25. CHANNEL_SEL Register

7	6	5	4	3	2	1	0
RESERVED				MANUAL_CHID[3:0]			
R-0b				R/W-0b			

Table 21. CHANNEL_SEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0b	Reserved. Reads return 0b.
3-0	MANUAL_CHID[3:0]	R/W	0b	In manual mode, this field contains the 4-bit channel ID of the analog input channel for next ADC conversion. For valid ADC data, the channel ID must not be configured as GPIO. 0b = CH0 1b = CH5 10b = CH6 11b = CH3 100b = CH4 111b = CH7 1000b = Reserved.

7.6.13 AUTO_SEQ_CHSEL Register (Address = 0x12) [reset = 0x0]

AUTO_SEQ_CHSEL is shown in Figure 26 and described in Table 22.

Return to the Summary Table.

Figure 26. AUTO_SEQ_CHSEL Register

7	6	5	4	3	2	1	0
AUTO_SEQ_CHSEL[7:0]							
R/W-0b							

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Table 22. AUTO_SEQ_CHSEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	AUTO_SEQ_CHSEL[7:0]	R/W	0b	Enable analog input channels AIN7 through AIN0 in auto sequencing mode. 0b = Analog input channel is not enabled in scanning sequence. 1b = Analog input channel is enabled in scanning sequence.

ADVANCE INFORMATION

8 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The two primary circuits required to maximize the performance of a high-precision, successive approximation register (SAR), analog-to-digital converter (ADC) are the input driver and the reference driver circuits. This section details some general principles for designing the input driver circuit, reference driver circuit, and provides some application circuits designed for the TLA2528.

8.2 Typical Applications

8.2.1 Mixed-Channel Configuration

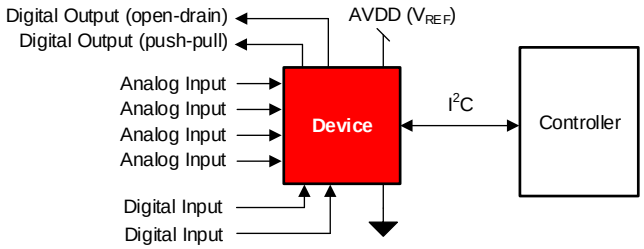


图 27. DAQ Circuit: Single-Supply DAQ

8.2.1.1 Design Requirements

The goal of this application is to configure some channels of the TLA2528 as digital inputs, open-drain digital outputs, and push-pull digital outputs.

8.2.1.2 Detailed Design Procedure

The TLA2528 can support GPIO functionality at each input pin. Any analog input pin can be independently configured as a digital input, a digital open-drain output, or a digital push-pull output though the PIN_CFG and GPIO_CFG registers; see 表 3.

8.2.1.2.1 Digital Input

The digital input functionality can be used to monitor a signal within the system. 图 28 illustrates that the state of the digital input can be read from the GPI_VALUE register.

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Typical Applications (接下页)

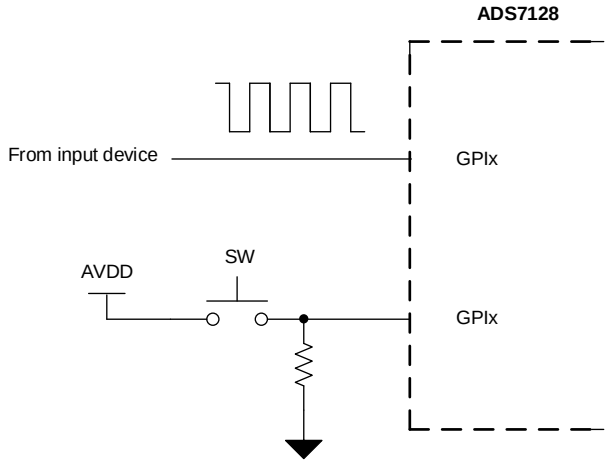


图 28. Digital Input

8.2.1.2.2 Digital Open-Drain Output

The channels of the TLA2528 can be configured as digital open-drain outputs supporting an output voltage up to 5.5 V. An open-drain output, as shown in 图 29, consists of an internal FET (Q) connected to ground. The output is idle when not driven by the device, which means Q is off and the pull-up resistor, R_{PULL_UP}, connects the GPOx node to the desired output voltage. The output voltage can range anywhere up to 5.5 V, depending on the external voltage that the GPIOx is pulled up to. When the device is driving the output, Q turns on, thus connecting the pull-up resistor to ground and bringing the node voltage at GPOx low.

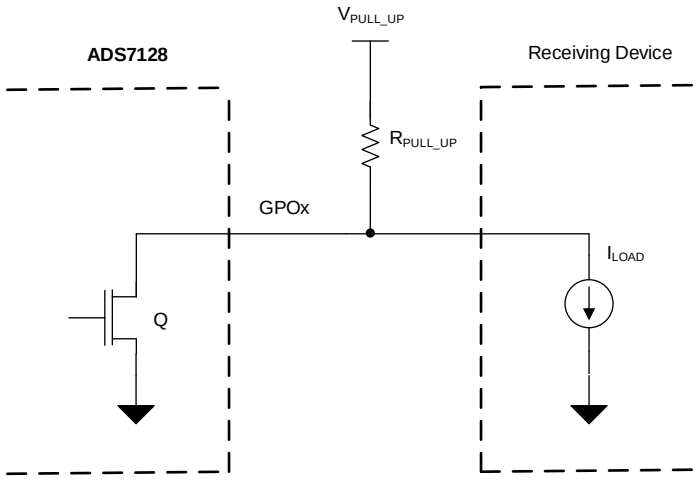


图 29. Digital Open-Drain Output

The minimum value of the pullup resistor, as calculated in 公式 3, is given by the ratio of V_{PULL_UP} and the maximum current supported by the device digital output (5 mA).

$$R_{MIN} = (V_{PULL_UP} / 5\ mA) \quad (3)$$

The maximum value of the pullup resistor, as calculated in 公式 4, depends on the minimum input current requirement, I_{LOAD}, of the receiving device driven by this GPIO.

$$R_{MAX} = (V_{PULL_UP} / I_{LOAD}) \quad (4)$$

Select R_{PULL_UP} such that $R_{MIN} < R_{PULL_UP} < R_{MAX}$.

ADVANCE INFORMATION

Typical Applications (接下页)

8.2.1.3 Digital Push-Pull Output

The channels of the TLA2528 can be configured as digital push-pull outputs supporting an output voltage up to AVDD. As shown in 图 30, a push-pull output consists of two mirrored opposite bipolar transistors, Q1 and Q2. The device can both source and sink current because only one transistor is on at a time (either Q2 is on and pulls the output low, or Q1 is on and sets the output high). A push-pull configuration always drives the line opposed to an open-drain output where the line is left floating.

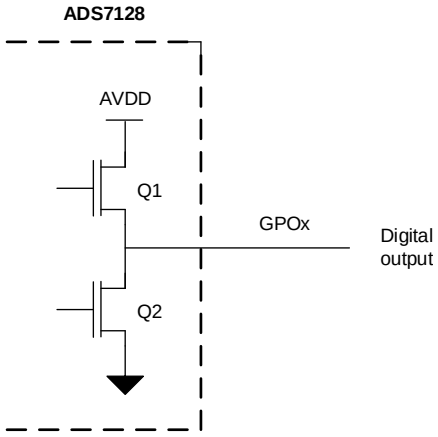


图 30. Digital Push-Pull Output

9 Power Supply Recommendations

9.1 AVDD and DVDD Supply Recommendations

The TLA2528 has two separate power supplies: AVDD and DVDD. The device operates on AVDD; DVDD is used for the interface circuits. For supplies greater than 2.35 V, AVDD and DVDD can be shorted externally if single-supply operation is desired. The AVDD supply also defines the full-scale input range of the device. Decouple the AVDD and DVDD pins individually, as shown in 图 31, with 1-µF ceramic decoupling capacitors. The minimum capacitor value required for AVDD and DVDD is 200 nF and 20 nF, respectively. If both supplies are powered from the same source, a minimum capacitor value of 220 nF is required for decoupling.

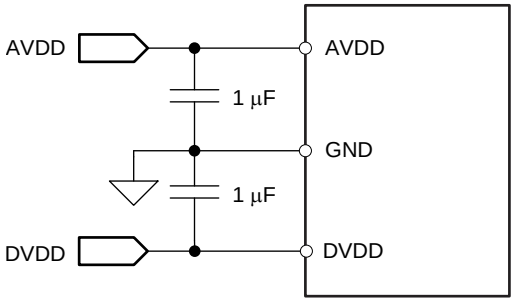


图 31. Power-Supply Decoupling

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10 Layout

10.1 Layout Guidelines

图 32 shows a board layout example for the TLA2528. Avoid crossing digital lines with the analog signal path and keep the analog input signals and the AVDD supply away from noise sources.

Use 1-µF ceramic bypass capacitors in close proximity to the analog (AVDD) and digital (DVDD) power-supply pins. Avoid placing vias between the AVDD and DVDD pins and the bypass capacitors. Connect the GND pin to the ground plane using short, low-impedance paths. The AVDD supply voltage also functions as the reference voltage for the TLA2528. Place the decoupling capacitor (C_{REF}) for AVDD close to the device AVDD and GND pins and connect C_{REF} to the device pins with thick copper tracks.

10.2 Layout Example

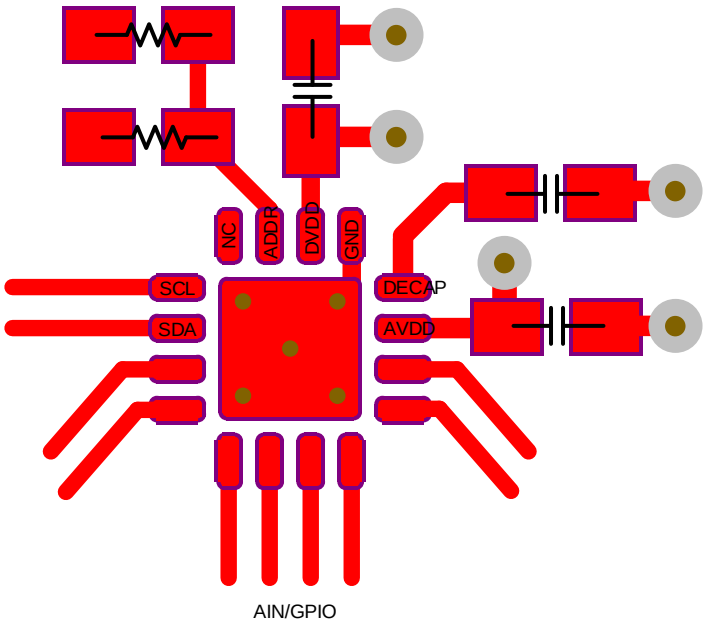


图 32. Example Layout

ADVANCE INFORMATION

11 器件和文档支持

11.1 接收文档更新通知

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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。 精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.5 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

ADVANCE INFORMATION

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLA2528IRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2528
TLA2528IRTER.A	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2528
TLA2528IRTERG4	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2528
TLA2528IRTERG4.A	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2528
TLA2528IRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	2528
TLA2528IRTET.A	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	2528

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

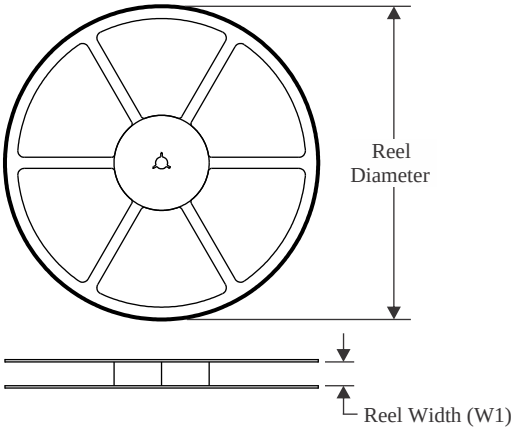
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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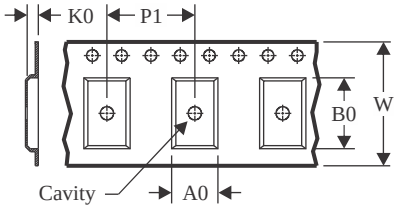
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

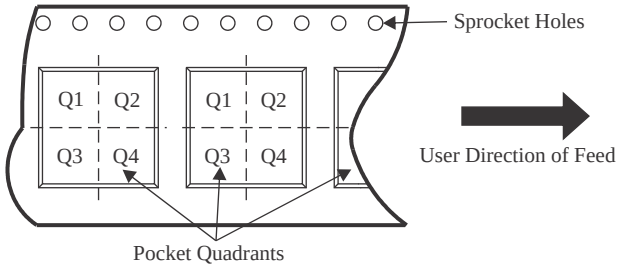


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

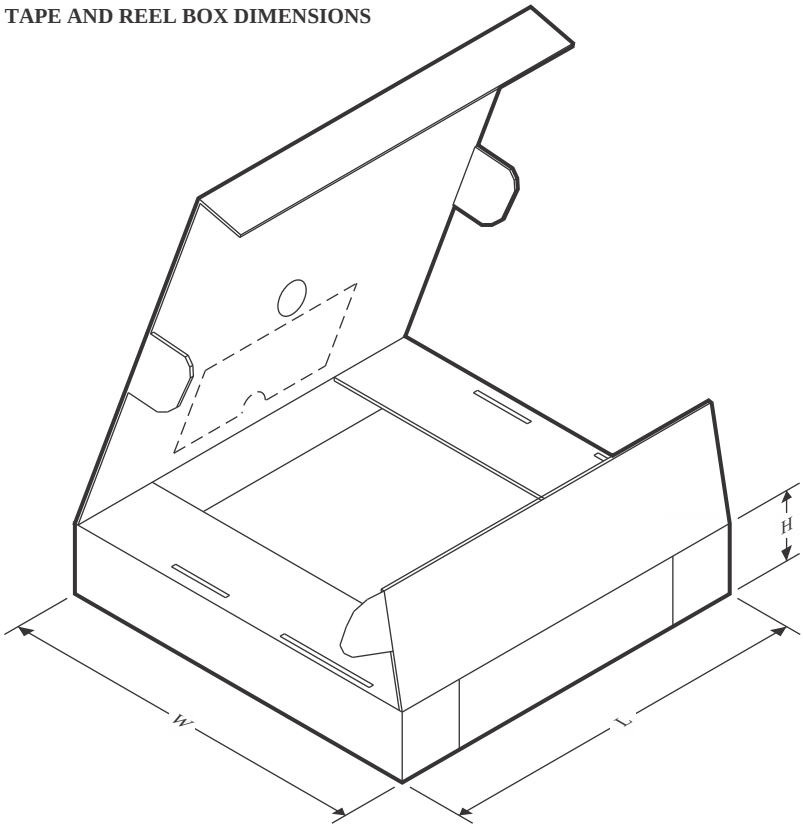
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLA2528IRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TLA2528IRTERG4	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TLA2528IRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLA2528IRTER	WQFN	RTE	16	3000	360.0	360.0	36.0
TLA2528IRTERG4	WQFN	RTE	16	3000	367.0	367.0	35.0
TLA2528IRTET	WQFN	RTE	16	250	210.0	185.0	35.0

GENERIC PACKAGE VIEW

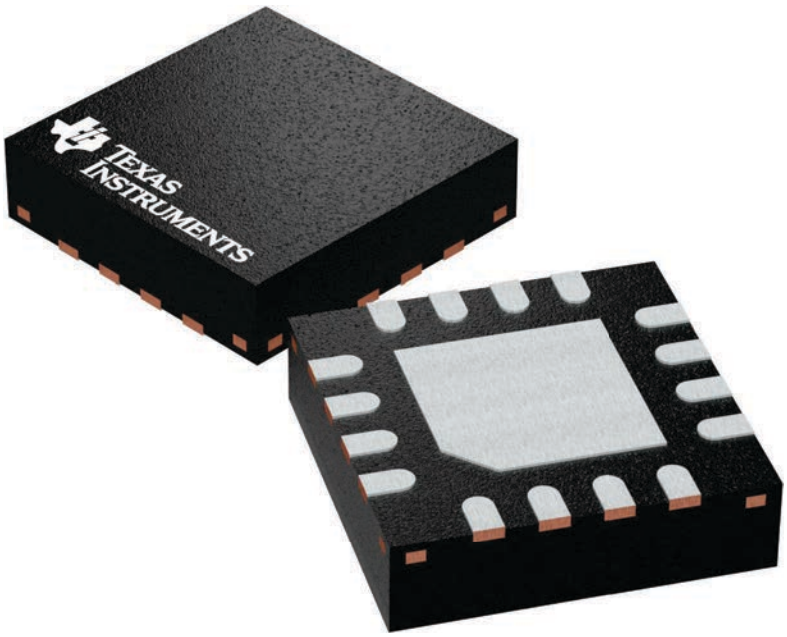
RTE 16

WQFN - 0.8 mm max height

3 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

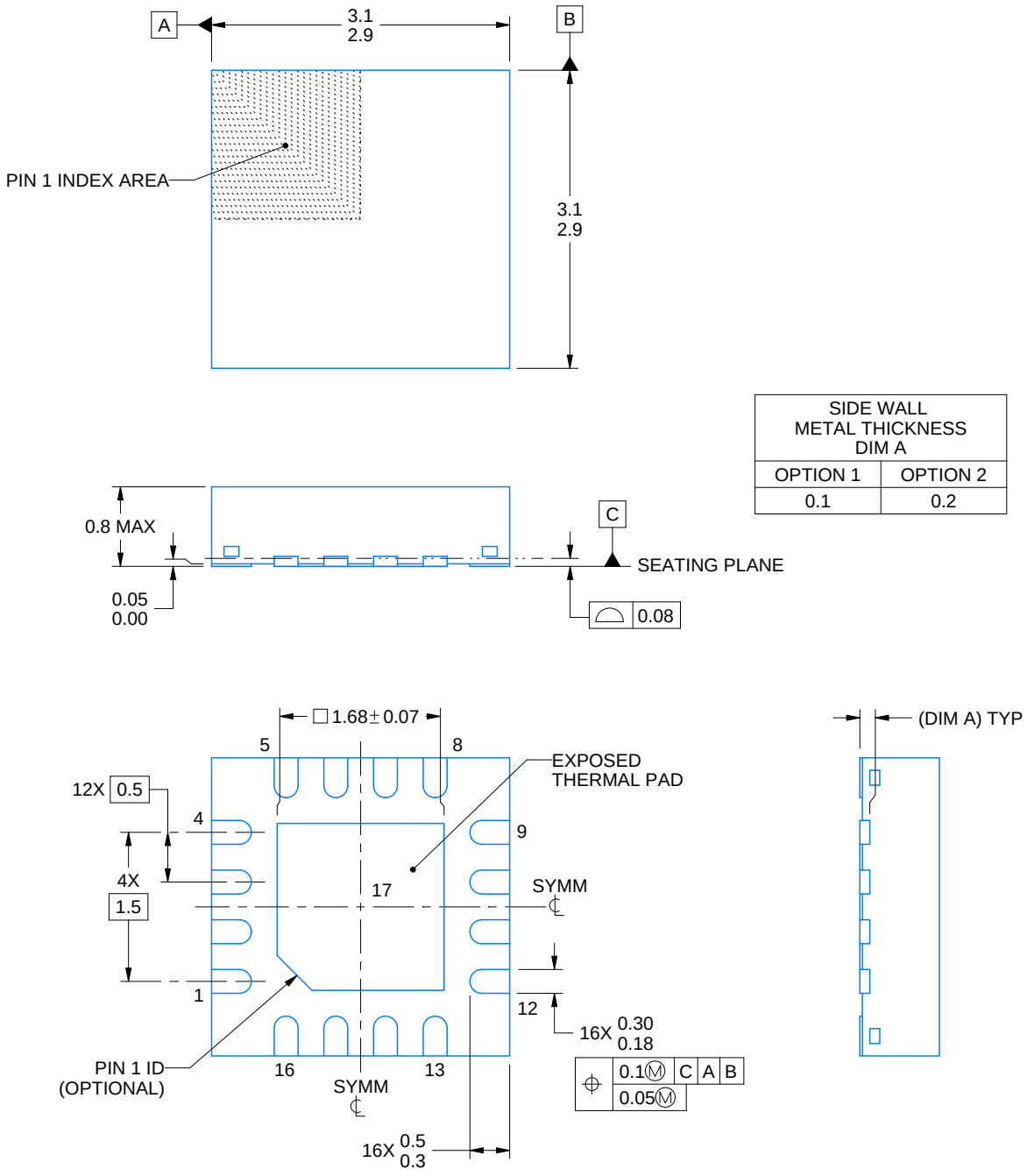


RTE0016C

PACKAGE OUTLINE

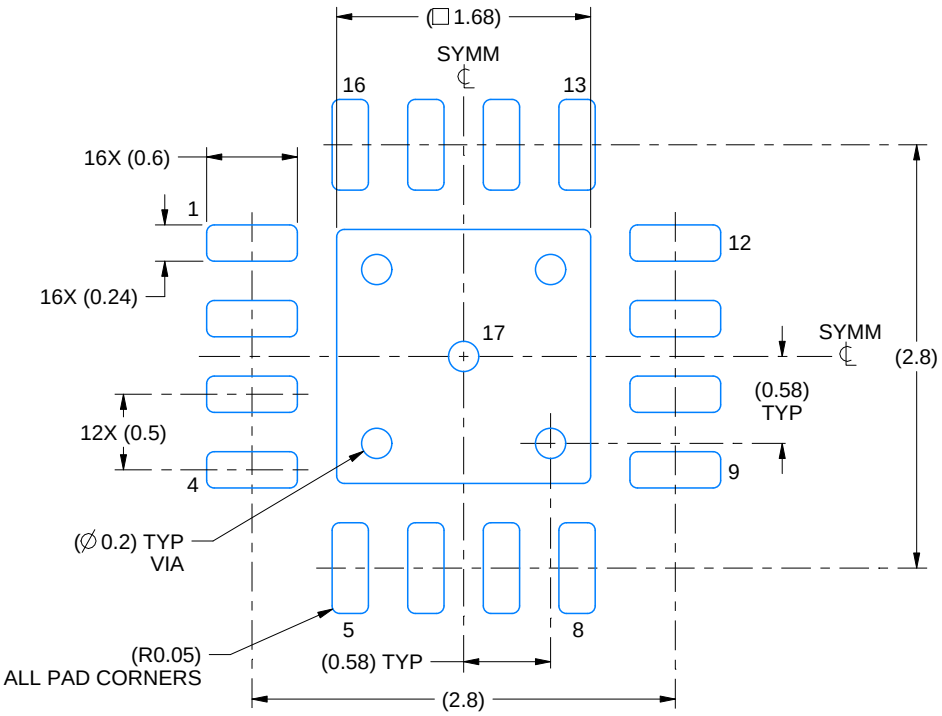
WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

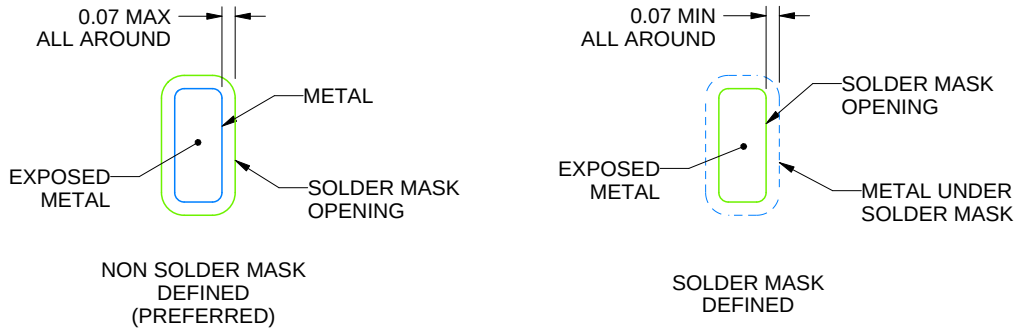


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:20X

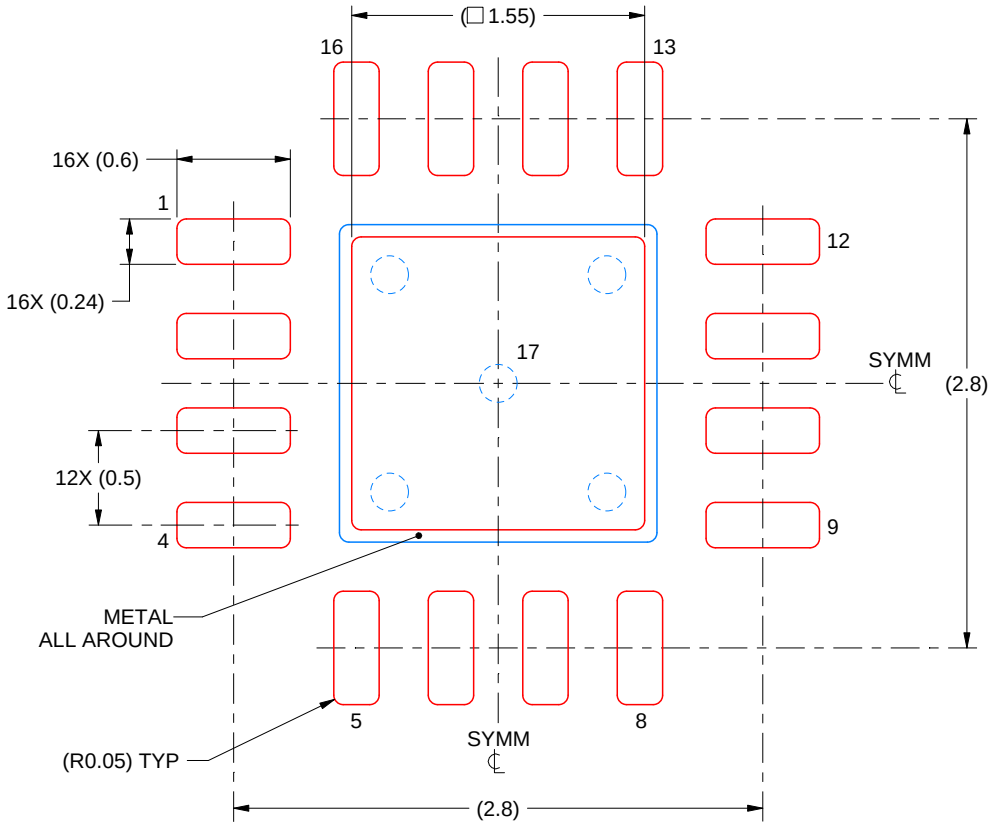


SOLDER MASK DETAILS

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NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 17:
85% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:25X

4219117/B 04/2022

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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